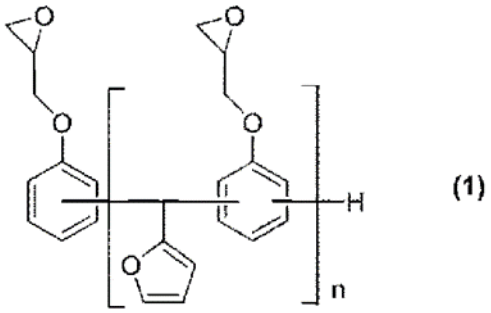
CLAIMS

[Claim 1] A curable resin composition, comprising an epoxy resin represented by the following formula (1) and a biomass-modified acid anhydride,

wherein the biomass-modified acid anhydride is at least one selected from myrcene-modified acid anhydride, farnesene-modified acid anhydride, and α-terpinene-modified acid anhydride,

[Chemical Formula 1]



(1)

(in formula (1), n is an average value of the number of repetitions and represents a real number where $1<n<15$).

[Claim 2] The curable resin composition according to claim 1, wherein biomass content of the biomass-modified acid anhydride is 20% or more.

[Claim 3] The curable resin composition according to claim 1, wherein ICI viscosity (150°C) of the epoxy resin is 0.01 to 0.20 Pa·s.

[Claim 4] The curable resin composition according to claim 1, wherein biomass content is 20% or more.

[Claim 5] The curable resin composition according to any one of claims 1 to 4, which is for a carbon fiber reinforced plastic.

[Claim 6] The curable resin composition according to any one of claims 1 to 4, which is for a semiconductor device encapsulant.

[Claim 7] The curable resin composition according to any one of claims 1 to 4, which is for a printed wiring board.

[Claim 8] A cured product, obtained by curing the curable resin composition according to any one of claims 1 to 4.